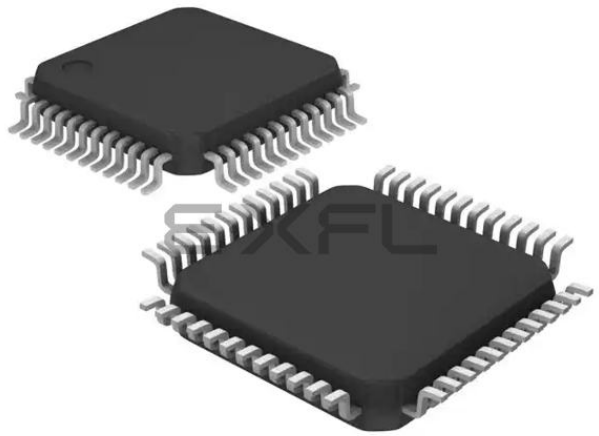

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	45MHz
Connectivity	I²C, IrDA, Microwire, SPI, SSI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, WDT
Number of I/O	39
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1225fbd48-301-1

- Crystal oscillator with an operating range of 1 MHz to 25 MHz.
- 12 MHz Internal RC (IRC) oscillator trimmed to 1 % accuracy that can optionally be used as a system clock.
- PLL allows CPU operation up to the maximum CPU rate without the need for a high-frequency crystal. May be run from the system oscillator or the internal RC oscillator.
- Clock output function with divider that can reflect the system oscillator clock, IRC clock, main clock, and Watchdog clock.
- Real-Time Clock (RTC).

- Digital peripherals
  - Micro DMA controller with 21 channels.
  - CRC engine.
  - Two UARTs with fractional baud rate generation and internal FIFO. One UART with RS-485 and modem support and one standard UART with IrDA.
  - SSP/SPI controller with FIFO and multi-protocol capabilities.
  - I^2C-bus interface supporting full I^2C-bus specification and Fast-mode Plus with a data rate of 1 Mbit/s with multiple address recognition and monitor mode. I^2C-bus pins have programmable glitch filter.
  - Up to 55 General Purpose I/O (GPIO) pins with programmable pull-up resistor, open-drain mode, programmable digital input glitch filter, and programmable input inverter.
  - Programmable output drive on all GPIO pins. Four pins support high-current output drivers.
  - All GPIO pins can be used as edge and level sensitive interrupt sources.
  - Four general purpose counter/timers with four capture inputs and four match outputs (32-bit timers) or two capture inputs and two match outputs (16-bit timers).
  - Windowed WatchDog Timer (WWDT); IEC-60335 Class B certified.
- Analog peripherals
  - One 8-channel, 10-bit ADC.
  - Two highly flexible analog comparators. Comparator outputs can be programmed to trigger a timer match signal or can be used to emulate 555 timer behavior.
- Power
  - Three reduced power modes: Sleep, Deep-sleep, and Deep power-down.
  - Processor wake-up from Deep-sleep mode via start logic using 12 port pins.
  - Processor wake-up from Deep-power down and Deep-sleep modes via the RTC.
  - Brownout detect with three separate thresholds each for interrupt and forced reset.
  - Power-On Reset (POR).
  - Integrated PMU (Power Management Unit).
- Unique device serial number for identification.
- 3.3 V power supply.
- Available as 64-pin and 48-pin LQFP package.

3. Applications

- eMetering
- Lighting
- Industrial networking
- Alarm systems
- White goods

4. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
LPC1227FBD64/301	LQFP64	LQFP64: plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1226FBD64/301	LQFP64	LQFP64: plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1225FBD64/321	LQFP64	LQFP64: plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1225FBD64/301	LQFP64	LQFP64: plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1224FBD64/121	LQFP64	LQFP64: plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1224FBD64/101	LQFP64	LQFP64: plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1227FBD48/301	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1226FBD48/301	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1225FBD48/321	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1225FBD48/301	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1224FBD48/121	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1224FBD48/101	LQFP48	LQFP48: plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2

Table 3. LPC122x pin description *…continued*

Symbol	Pin LQFP48	Pin LQFP64		Start logic input	Type	Reset state [1]	Description
PIO0_7/$\overline{\text{CTS0}}$/ CT32B1_CAP1/ CT32B1_MAT1	22	26	[2] [3]	yes	I/O	I; PU	**PIO0_7 —** General purpose digital input/output pin.
					I	-	**$\overline{\text{CTS0}}$ —** Clear To Send input for UART0.
					I	-	**CT32B1_CAP1 —** Capture input, channel 1 for 32-bit timer 1.
					O	-	**CT32B1_MAT1 —** Match output, channel 1 for 32-bit timer 1.
PIO0_8/RXD1/ CT32B1_CAP2/ CT32B1_MAT2	23	27	[2] [3]	yes	I/O	I; PU	**PIO0_8 —** General purpose digital input/output pin.
					I	-	**RXD1 —** Receiver input for UART1.
					I	-	**CT32B1_CAP2 —** Capture input, channel 2 for 32-bit timer 1.
					O	-	**CT32B1_MAT2 —** Match output, channel 2 for 32-bit timer 1.
PIO0_9/TXD1/ CT32B1_CAP3/ CT32B1_MAT3	24	28	[2] [3]	yes	I/O	I; PU	**PIO0_9 —** General purpose digital input/output pin.
					O	-	**TXD1 —** Transmitter output for UART1.
					I	-	**CT32B1_CAP3 —** Capture input, channel 3 for 32-bit timer 1.
					O	-	**CT32B1_MAT3 —** Match output, channel 3 for 32-bit timer 1.
PIO0_10/SCL	25	37	[4]	yes	I/O	I; IA	**PIO0_10 —** General purpose digital input/output pin.
					I/O	-	**SCL —** I^2C-bus clock input/output.
PIO0_11/SDA/ CT16B0_CAP0/ CT16B0_MAT0	26	38	[4]	yes	I/O	I; IA	**PIO0_11 —** General purpose digital input/output pin.
					I/O	-	**SDA —** I^2C-bus data input/output.
					I	-	**CT16B0_CAP0 —** Capture input, channel 0 for 16-bit timer 0.
					O	-	**CT16B0_MAT0 —** Match output, channel 0 for 16-bit timer 0.
PIO0_12/CLKOUT/ CT16B0_CAP1/ CT16B0_MAT1	27	39	[9]	no	I/O	I; PU	**PIO0_12 —** General purpose digital input/output pin. A LOW level on this pin during reset starts the ISP command handler. High-current output driver.
					O	-	**CLKOUT —** Clock out pin.
					I	-	**CT16B0_CAP1 —** Capture input, channel 1 for 16-bit timer 0.
					O	-	**CT16B0_MAT1 —** Match output, channel 1 for 16-bit timer 0.
$\overline{\text{RESET}}$/PIO0_13	28	40	[5] [3]	no	I	I; PU	**$\overline{\text{RESET}}$ —** External reset input: A LOW on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0.
					I/O	-	**PIO0_13 —** General purpose digital input/output pin.
PIO0_14/SCK	29	41	[2] [3]	no	I/O	I; PU	**PIO0_14 —** General purpose digital input/output pin.
					I/O	-	**SCK —** Serial clock for SSP/SPI.
PIO0_15/SSEL/ CT16B1_CAP0/ CT16B1_MAT0	30	42	[2] [3]	no	I/O	I; PU	**PIO0_15 —** General purpose digital input/output pin.
					I/O	-	**SSEL —** Slave select for SSP/SPI.
					I	-	**CT16B1_CAP0 —** Capture input, channel 0 for 16-bit timer 1.
					O	-	**CT16B1_MAT0 —** Match output, channel 0 for 16-bit timer 1.
PIO0_16/MISO/ CT16B1_CAP1/ CT16B1_MAT1	31	43	[2] [3]	no	I/O	I; PU	**PIO0_16 —** General purpose digital input/output pin.
					I/O	-	**MISO —** Master In Slave Out for SSP/SPI.
					I	-	**CT16B1_CAP1 —** Capture input, channel 1 for 16-bit timer 1.
					O	-	**CT16B1_MAT1 —** Match output, channel 1 for 16-bit timer 1.

Table 3. LPC122x pin description *…continued*

Symbol	Pin LQFP48	Pin LQFP64		Start logic input	Type	Reset state [1]	Description
PIO2_6/ CT32B0_CAP2/ CT32B0_MAT2/DCD0	-	35	[2] [3]	no	I/O	I; PU	**PIO2_6 —** General purpose digital input/output pin.
					I	-	**CT32B0_CAP2 —** Capture input, channel 2 for 32-bit timer 0.
					O	-	**CT32B0_MAT2 —** Match output, channel 2 for 32-bit timer 0.
					I	-	**DCD0 —** Data Carrier Detect input for UART0.
PIO2_7/ CT32B0_CAP3/ CT32B0_MAT3/DSR0	-	36	[2] [3]	no	I/O	I; PU	**PIO2_7 —** General purpose digital input/output pin.
					I	-	**CT32B0_CAP3 —** Capture input, channel 3 for 32-bit timer 0.
					O	-	**CT32B0_MAT3 —** Match output, channel 3 for 32-bit timer 0.
					I	-	**DSR0 —** Data Set Ready input for UART0.
PIO2_8/ CT32B1_CAP0/ CT32B1_MAT0	-	59	[2] [3]	no	I/O	I; PU	**PIO2_8 —** General purpose digital input/output pin.
					I	-	**CT32B1_CAP0 —** Capture input, channel 0 for 32-bit timer 1.
					O	-	**CT32B1_MAT0 —** Match output, channel 0 for 32-bit timer 1.
PIO2_9/ CT32B1_CAP1/ CT32B1_MAT1	-	60	[2] [3]	no	I/O	I; PU	**PIO2_9 —** General purpose digital input/output pin.
					I	-	**CT32B1_CAP1 —** Capture input, channel 1 for 32-bit timer 1.
					O	-	**CT32B1_MAT1 —** Match output, channel 1 for 32-bit timer 1.
PIO2_10/ CT32B1_CAP2/ CT32B1_MAT2/TXD1	-	61	[2] [3]	no	I/O	I; PU	**PIO2_10 —** General purpose digital input/output pin.
					I	-	**CT32B1_CAP2 —** Capture input, channel 2 for 32-bit timer 1.
					O	-	**CT32B1_MAT2 —** Match output, channel 2 for 32-bit timer 1.
					O	-	**TXD1 —** Transmitter output for UART1.
PIO2_11/ CT32B1_CAP3/ CT32B1_MAT3/RXD1	-	62	[2] [3]	no	I/O	I; PU	**PIO2_11 —** General purpose digital input/output pin.
					I	-	**CT32B1_CAP3 —** Capture input, channel 3 for 32-bit timer 1.
					O	-	**CT32B1_MAT3 —** Match output, channel 3 for 32-bit timer 1.
					I	-	**RXD1 —** Receiver input for UART1.
PIO2_12/RXD1	-	13	[2] [3]	no	I/O	I; PU	**PIO2_12 —** General purpose digital input/output pin.
					I	-	**RXD1 —** Receiver input for UART1.
PIO2_13/TXD1	-	14	[2] [3]	no	I/O	I; PU	**PIO2_13 —** General purpose digital input/output pin.
					O	-	**TXD1 —** Transmitter output for UART1.
PIO2_14	-	15	[2] [3]	no	I/O	I; PU	**PIO2_14 —** General purpose digital input/output pin.
PIO2_15	-	16	[2] [3]	no	I/O	I; PU	**PIO2_15 —** General purpose digital input/output pin.
RTCXIN	46	58	[10]	-	I	-	Input to the 32 kHz oscillator circuit.
RTCXOUT	45	57	[10]	-	O	-	Output from the 32 kHz oscillator amplifier.
XTALIN	1	1		-	I	-	Input to the system oscillator circuit and internal clock generator circuits.
XTALOUT	2	2		-	O	-	Output from the system oscillator amplifier.
VREF_CMP	3	3		-	I	-	Reference voltage for comparator.

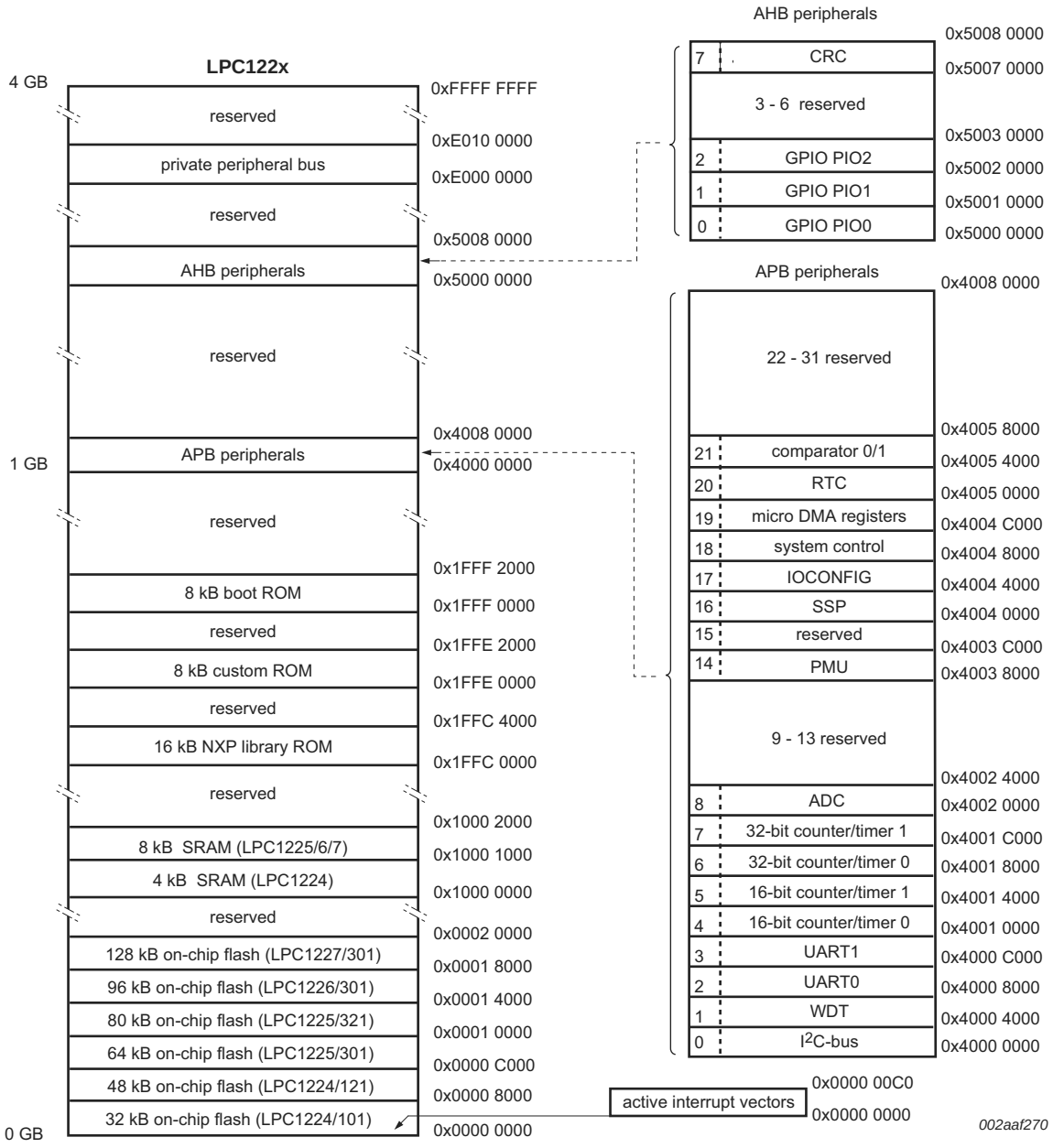


Fig 4. LPC122x memory map

7.5 Nested Vectored Interrupt Controller (NVIC)

The Nested Vectored Interrupt Controller (NVIC) is an integral part of the Cortex-M0. The tight coupling to the CPU allows for low interrupt latency and efficient processing of late arriving interrupts.

7.5.1 Features

- Controls system exceptions and peripheral interrupts.

- In the LPC122x, the NVIC supports 32 vectored interrupts. In addition, up to 12 of the individual GPIO inputs are NVIC-vector capable.
- Four programmable interrupt priority levels with hardware priority level masking.
- Software interrupt generation.
- Non-maskable Interrupt (NMI) can be programmed to use any of the peripheral interrupts. The NMI is not available on an external pin.

7.5.2 Interrupt sources

Each peripheral device has one interrupt line connected to the NVIC but may have several interrupt flags. Individual interrupt flags may also represent more than one interrupt source.

Any GPIO pin (total of up to 55 pins) regardless of the selected function, can be programmed to generate an interrupt on a level, a rising edge or falling edge, or both.

7.6 IOCONFIG block

The IOCONFIG block allows selected pins of the microcontroller to have more than one function. Configuration registers control the multiplexers to allow connection between the pin and the on-chip peripherals.

Peripherals should be connected to the appropriate pins prior to being activated and prior to any related interrupt(s) being enabled. Activity of any enabled peripheral function that is not mapped to a related pin should be considered undefined.

7.6.1 Features

- Programmable pull-up resistor.
- Programmable digital glitch filter.
- Programmable input inverter.
- Programmable drive current.
- Programmable open-drain mode.

7.7 Micro DMA controller

The micro DMA controller enables memory-to-memory, memory-to-peripheral, and peripheral-to-memory data transfers. The supported peripherals are: UART0 (transmit and receive), UART1 (transmit and receive), SSP/SPI (transmit and receive), ADC, RTC, 32-bit counter/timer 0 (match output channels 0 and 1), 32-bit counter/timer 1 (match output channels 0 and 1), 16-bit counter/timer 0 (match output channel 0), 16-bit counter/timer 1 (match output channel 0), comparator 0, comparator 1, GPIO0 to GPIO2.

7.7.1 Features

- Single AHB-Lite master for transferring data using a 32-bit address bus and 32-bit data bus.
- 21 DMA channels.
- Handshake signals and priority level programmable for each channel.
- Each priority level arbitrates using a fixed priority that is determined by the DMA channel number.

7.10.1 Features

- 16-byte Receive and Transmit FIFOs.
- Register locations conform to 16C550 industry standard.
- Receiver FIFO trigger points at 1 B, 4 B, 8 B, and 14 B.
- Built-in fractional baud rate generator covering wide range of baud rates without a need for external crystals of particular values.
- Auto-baud capabilities and FIFO control mechanism that enables software flow control implementation.
- Support for RS-485/9-bit mode (UART0).
- Support for modem control (UART0).

7.11 SSP/SPI serial I/O controller

The LPC122x contain one SSP/SPI controller. The SSP/SPI controller is capable of operation on a SSP, 4-wire SSI, or Microwire bus. It can interact with multiple masters and slaves on the bus. Only a single master and a single slave can communicate on the bus during a given data transfer. The SSP supports full duplex transfers, with frames of 4 bits to 16 bits of data flowing from the master to the slave and from the slave to the master. In practice, often only one of these data flows carries meaningful data.

7.11.1 Features

- Compatible with Motorola SPI, 4-wire Texas Instruments SSI, and National Semiconductor Microwire buses
- Synchronous serial communication
- Master or slave operation
- 8-frame FIFOs for both transmit and receive
- 4-bit to 16-bit frame

7.12 I^2C-bus serial I/O controller

The LPC122x contain one I^2C-bus controller.

The I^2C-bus is bidirectional for inter-IC control using only two wires: a serial clock line (SCL) and a serial data line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (e.g., an LCD driver) or a transmitter with the capability to both receive and send information (such as memory). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I^2C is a multi-master bus and can be controlled by more than one bus master connected to it.

7.12.1 Features

- The I^2C-interface is a standard I^2C-compliant bus interface with open-drain pins and supports I^2C Fast-mode Plus with bit rates of up to 1 Mbit/s.
- Programmable digital glitch filter providing a 60 ns to 1 μs input filter.
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.

- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I^2C-bus can be used for test and diagnostic purposes.
- The I^2C-bus controller supports multiple address recognition and a bus monitor mode.

7.13 10-bit ADC

The LPC122x contains one ADC. It is a single 10-bit successive approximation ADC with eight channels.

7.13.1 Features

- 10-bit successive approximation ADC.
- Input multiplexing among 8 pins.
- Power-down mode.
- Measurement range 0 V to $V_{DD(3V3)}$.
- 10-bit conversion time of 257 kHz.
- Burst conversion mode for single or multiple inputs.
- Optional conversion on transition of input pin or counter/timer match signal.
- Individual result registers for each ADC channel to reduce interrupt overhead.

7.14 Comparator block

The comparator block consists of two analog comparators.

7.14.1 Features

- Up to six selectable external sources per comparator; fully configurable on either positive or negative comparator input channels.
- BOD 0.9 V internal reference voltage selectable on both comparators; configurable on either positive or negative comparator input channels.
- 32-stage voltage ladder internal reference voltage selectable on both comparators; configurable on either positive or negative comparator input channels.
- Voltage ladder source voltage is selectable from an external pin or an internal 3.3 V voltage rail if external power source is not available.
- Voltage ladder can be separately powered down for applications only requiring the comparator function.
- Relaxation oscillator circuitry output for a feedback 555-style timer application.
- Common interrupt connected to NVIC.
- Comparator outputs selectable as synchronous or asynchronous.

The system oscillator operates at frequencies of 1 MHz to 25 MHz. This frequency can be boosted to a higher frequency, up to the maximum CPU operating frequency, by the system PLL. The ARM processor clock frequency is referred to as CCLK elsewhere in this document.

7.18.1.3 Watchdog oscillator

The watchdog oscillator can be used as a clock source that directly drives the CPU, the watchdog timer, or the CLKOUT pin. The watchdog oscillator nominal frequency is programmable between 7.8 kHz and 1.7 MHz. The frequency spread over processing and temperature is ±40 %.

7.18.2 System PLL

The PLL accepts an input clock frequency in the range of 10 MHz to 25 MHz. The input frequency is multiplied up to a high frequency with a Current Controlled Oscillator (CCO). The multiplier can be an integer value from 1 to 32. The CCO operates in the range of 156 MHz to 320 MHz, so there is an additional divider in the loop to keep the CCO within its frequency range while the PLL is providing the desired output frequency. The output divider may be set to divide by 2, 4, 8, or 16 to produce the output clock. The PLL output frequency must be lower than 100 MHz. Since the minimum output divider value is 2, it is insured that the PLL output has a 50 % duty cycle. The PLL is turned off and bypassed following a chip reset and may be enabled by software. The program must configure and activate the PLL, wait for the PLL to lock, and then connect to the PLL as a clock source. The PLL settling time is 100 μs.

7.18.3 Clock output

The LPC122x features a clock output function that routes the IRC oscillator, the system oscillator, the watchdog oscillator, or the main clock to an output pin.

7.18.4 Wake-up process

The LPC122x begin operation at power-up and when awakened from Deep power-down mode by using the 12 MHz IRC oscillator as the clock source. This allows chip operation to resume quickly. If the main oscillator or the PLL is needed by the application, software will need to enable these features and wait for them to stabilize before they are used as a clock source.

7.18.5 Power control

The LPC122x support a variety of power control features. There are three special modes of processor power reduction: Sleep mode, Deep-sleep mode, and Deep power-down mode. The CPU clock rate may also be controlled as needed by changing clock sources, reconfiguring PLL values, and/or altering the CPU clock divider value. This allows a trade-off of power versus processing speed based on application requirements. In addition, a register is provided for shutting down the clocks to individual on-chip peripherals, allowing fine tuning of power consumption by eliminating all dynamic power use in any peripherals that are not required for the application. Selected peripherals have their own clock divider which provides even better power control.

7.18.5.1 Sleep mode

When Sleep mode is entered, the clock to the core is stopped. Resumption from the Sleep mode does not need any special sequence but re-enabling the clock to the ARM core.

7.20 Emulation and debugging

Debug functions are integrated into the ARM Cortex-M0. Serial wire debug is supported.

7.21 Integer division routines

The LPC122x contain performance-optimized integer division routines with support for up to 32-bit width in the numerator and denominator. Routines for signed and unsigned division and division with remainder are available. The integer division routines are ROM-based to reduce code-size.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).[1]

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DD(3V3)}$	supply voltage (3.3 V)			3.0	3.6	V
$V_{DD(IO)}$	input/output supply voltage			3.0	3.6	V
V_I	input voltage	on all digital pins	[2]	−0.5	+3.6	V
		on pins PIO0_10 and PIO0_11 (I^2C-bus pins)		0	5.5	V
I_{DD}	supply current	per supply pin	[3]	-	100	mA
I_{SS}	ground current	per ground pin	[3]	-	100	mA
I_{latch}	I/O latch-up current	$-(0.5V_{DD}) < V_I < (1.5V_{DD})$; $T_j < 125$ °C		-	100	mA
T_{stg}	storage temperature		[4]	−65	+150	°C
$P_{tot(pack)}$	total power dissipation (per package)	based on package heat transfer, not device power consumption		-	1.5	W
V_{ESD}	electrostatic discharge voltage	human body model; all pins	[5]	−8000	+8000	V

[1] The following applies to the limiting values:

a) This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

b) Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

[2] Including voltage on outputs in 3-state mode.

[3] The peak current is limited to 25 times the corresponding maximum current.

[4] Dependent on package type.

[5] Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.

Table 7. Static characteristics *…continued*
T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{OH}	HIGH-level output current	low mode; $V_{OH} = V_{DD(IO)} - 0.7$		20	-	-	mA
		high mode; $V_{OH} = V_{DD(IO)} - 0.7$		28	-	-	mA
I_{OL}	LOW-level output current	V_{OL} = 0.4 V low mode		12	-	-	mA
		high mode		18	-	-	mA
I_{OLS}	LOW-level short-circuit output current	$V_{OL} = V_{DD}$	[5]	-	-		mA
I_{pu}	pull-up current	V_I = 0 V		−50	−80	−100	μA
I^2C-bus pins (PIO0_10 and PIO0_11)							
V_{IH}	HIGH-level input voltage			$0.7V_{DD(IO)}$	-	-	V
V_{IL}	LOW-level input voltage			-	-	$0.3V_{DD(IO)}$	V
V_{hys}	hysteresis voltage			-	$0.05V_{DD(IO)}$	-	V
V_{OL}	LOW-level output voltage	I_{OLS} = 20 mA		-	-	0.4	V
I_{LI}	input leakage current	$V_I = V_{DD(IO)}$	[6]	-	2	4	μA
		V_I = 5 V		-	10	22	μA
C_i	capacitance for each I/O pin	on pins PIO0_10 and PIO0_11		-	-	8	pF
Oscillator pins							
$V_{i(xtal)}$	crystal input voltage	see Section 12.1		0	1.8	1.95	V
$V_{o(xtal)}$	crystal output voltage			0	1.8	1.95	V

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

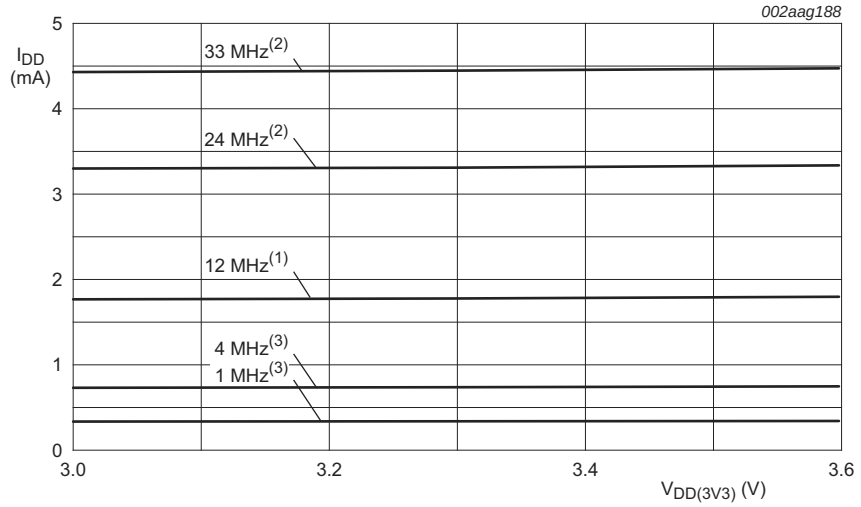
[2] Including voltage on outputs in 3-state mode.

[3] $V_{DD(3V3)}$ and $V_{DD(IO)}$ supply voltages must be present.

[4] 3-state outputs go into 3-state mode when $V_{DD(IO)}$ is grounded.

[5] Allowed as long as the current limit does not exceed the maximum current allowed by the device.

[6] To V_{SS}.



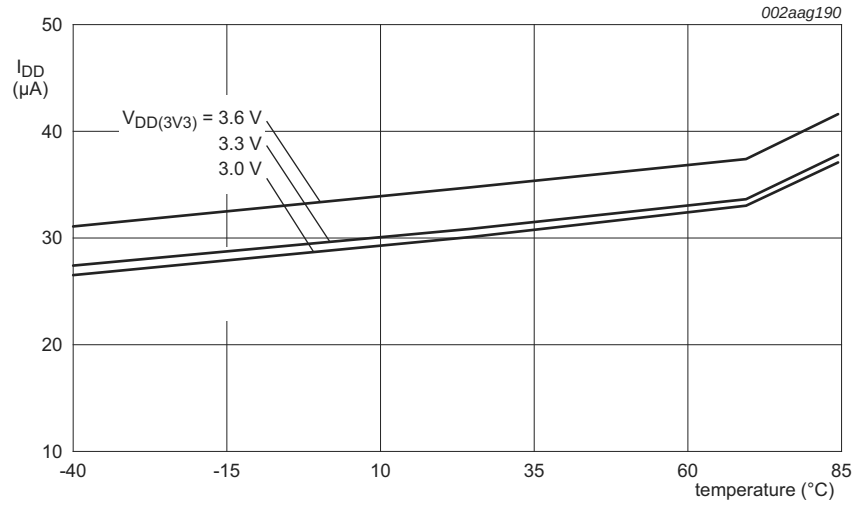
Conditions: $V_{DD(3V3)}$ = 3.3 V; sleep mode entered from flash; all peripherals disabled in the SYSAHBCLKCTRL register (SYSAHBCLKCTRL = 0x1F); all peripheral clocks disabled; internal pull-up resistors disabled; BOD disabled.

(1) System oscillator and system PLL disabled; IRC enabled.

(2) System oscillator and system PLL enabled; IRC disabled.

(3) System oscillator enabled with external clock input; IRC and system PLL disabled.

Fig 10. Sleep mode: Typical supply current I_{DD} versus supply voltage $V_{DD(3V3)}$ for different system clock frequencies



Conditions: BOD disabled; all oscillators and analog blocks disabled in the PDSLEEPCFG register

Fig 11. Deep-sleep mode: Typical supply current I_{DD} versus temperature for different supply voltages $V_{DD(3V3)}$

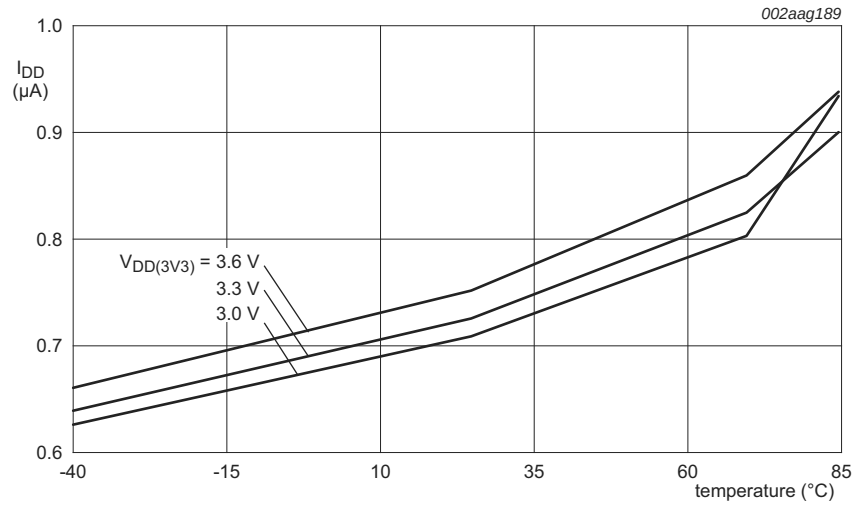
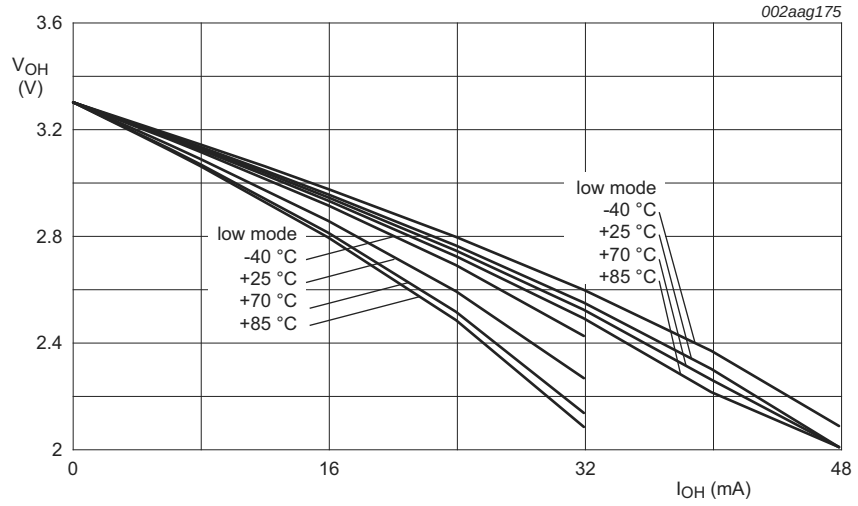


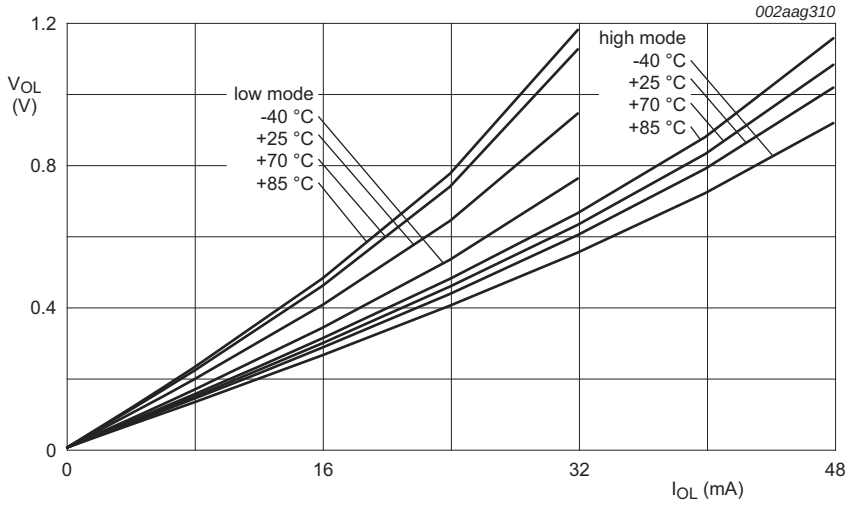
Fig 12. Deep power-down mode: Typical supply current I_{DD} versus temperature for different supply voltages $V_{DD(3V3)}$

10.3 Electrical pin characteristics



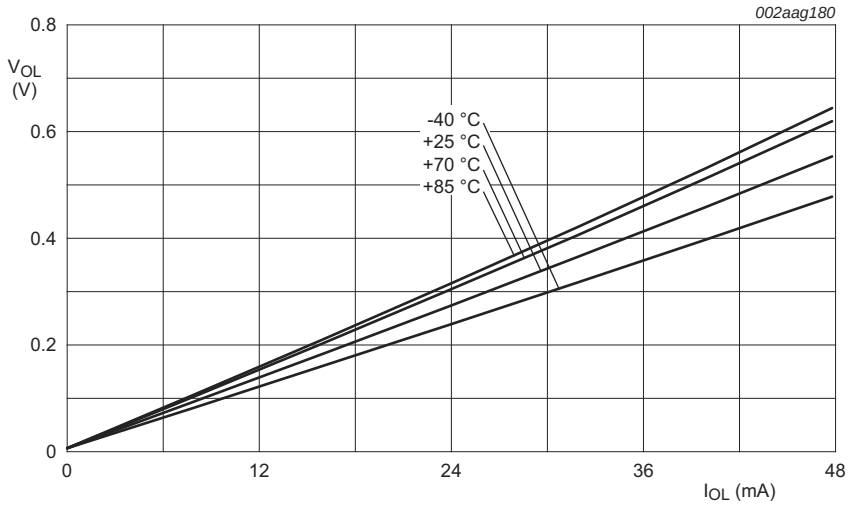
Conditions: $V_{DD(IO)}$ = 3.3 V

Fig 13. High-drive pins: Typical HIGH-level output voltage V_{OH} versus HIGH-level output current I_{OH}



Conditions: $V_{DD(IO)}$ = 3.3 V

Fig 14. High-drive pins: Typical LOW-level output voltage V_{OL} versus LOW-level output current I_{OL}



Conditions: $V_{DD(IO)}$ = 3.3 V.

Fig 15. I^2C-bus pins (high current sink): Typical LOW-level output voltage V_{OL} versus LOW-level output current I_{OL}

10.4 ADC characteristics

Table 9. ADC static characteristics

T_{amb} = −40 °C to +85 °C unless otherwise specified; ADC frequency 9 MHz, $V_{DD(3V3)}$ = 3.0 V to 3.6 V.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
V_{IA}	analog input voltage		0	-	$V_{DD(3V3)}$	V
C_{ia}	analog input capacitance		-	-	1	pF
E_D	differential linearity error	[2][3][4]	-	-	± 1	LSB
$E_{L(adj)}$	integral non-linearity	[2][5]	-	-	± 2.5	LSB
E_O	offset error	[2][6]	-	-	± 1	LSB
E_G	gain error	[2][7]	-	-	± 3	LSB
E_T	absolute error	[2][8]	-	-	± 3	LSB
$f_{c(ADC)}$	ADC conversion frequency		-	-	257	kHz
R_i	input resistance	[9][10]	-	-	3.9	MΩ

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] Conditions: V_{SS} = 0 V, $V_{DD(3V3)}$ = 3.3 V.

[3] The ADC is monotonic, there are no missing codes.

[4] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See Figure 19.

[5] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See Figure 19.

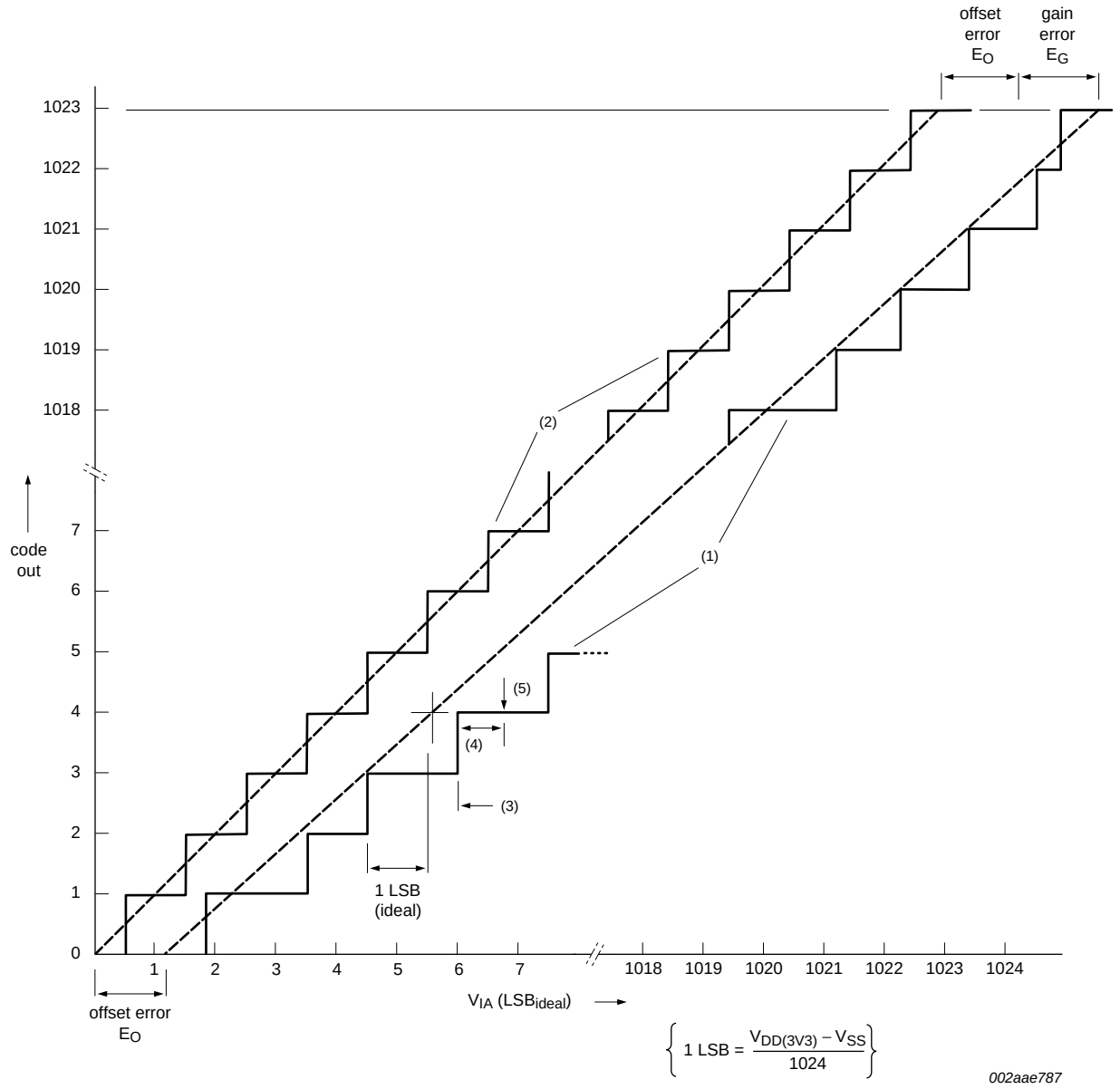
[6] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See Figure 19.

[7] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See Figure 19.

[8] The absolute error (E_T) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve. See Figure 19.

[9] T_{amb} = 25 °C; maximum sampling frequency f_s = 257 kHz and analog input capacitance C_{ia} = 1 pF.

[10] Input resistance R_i depends on the sampling frequency fs: $R_i = 1 / (f_s \times C_{ia})$.



(1) Example of an actual transfer curve.

(2) The ideal transfer curve.

(3) Differential linearity error (E_D).

(4) Integral non-linearity ($E_{L(adj)}$).

(5) Center of a step of the actual transfer curve.

Fig 19. ADC characteristics

11.2 Flash memory

Table 12. Dynamic characteristic: flash memory
T_{amb} = −40 °C to +85 °C; $V_{DD(3V3)}$ over specified ranges.

Symbol	Parameter	Conditions		Min	Max	Unit
t_{er}	erase time	for one page (512 byte)	[1]	-	20	ms
		for one sector (4 kB)	[1]		162	ms
		for all sectors; mass erase	[1]	-	20	ms
t_{prog}	programming time	one word (4 bytes)	[1]	-	49	µs
		four sequential words	[1]	-	194	µs
		128 bytes (one row of 32 words)	[1]	-	765	µs
N_{endu}	endurance		[2]	20000	-	cycles
t_{ret}	retention time			10	-	years

[1] Erase and programming times are valid over the lifetime of the device (minimum 20000 cycles).

[2] Number of program/erase cycles.

11.3 External clock

Table 13. Dynamic characteristic: external clock
T_{amb} = −40 °C to +85 °C; $V_{DD(3V3)}$ over specified ranges.[1]

Symbol	Parameter	Conditions	Min	Typ[2]	Max	Unit
f_{osc}	oscillator frequency		1	-	25	MHz
$T_{cy(clk)}$	clock cycle time		40	-	1000	ns
t_{CHCX}	clock HIGH time		$T_{cy(clk)} \times 0.4$	-	-	ns
t_{CLCX}	clock LOW time		$T_{cy(clk)} \times 0.4$	-	-	ns
t_{CLCH}	clock rise time		-	-	5	ns
t_{CHCL}	clock fall time		-	-	5	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

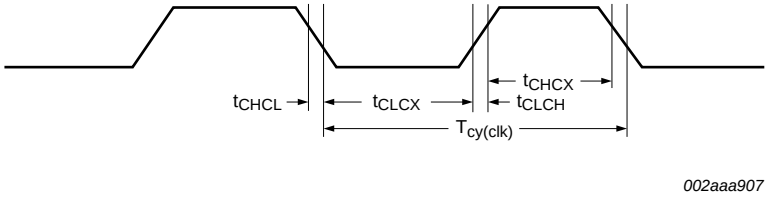


Fig 21. External clock timing (with an amplitude of at least $V_{i(RMS)}$ = 200 mV)

11.5 I²C-bus

Table 16. Dynamic characteristic: I²C-bus pins
T_{amb} = −40 °C to +85 °C.[1]

Symbol	Parameter		Conditions	Min	Max	Unit
f_{SCL}	SCL clock frequency		Standard-mode	0	100	kHz
			Fast-mode	0	400	kHz
			Fast-mode Plus	0	1	MHz
t_f	fall time	[3][4][5][6]	of both SDA and SCL signals	-	300	ns
			Standard-mode			
			Fast-mode	$20 + 0.1 \times C_b$	300	ns
			Fast-mode Plus	-	120	ns
t_{LOW}	LOW period of the SCL clock		Standard-mode	4.7	-	µs
			Fast-mode	1.3	-	µs
			Fast-mode Plus	0.5	-	µs
t_{HIGH}	HIGH period of the SCL clock		Standard-mode	4.0	-	µs
			Fast-mode	0.6	-	µs
			Fast-mode Plus	0.26	-	µs
$t_{HD;DAT}$	data hold time	[2][3][7]	Standard-mode	0	-	µs
			Fast-mode	0	-	µs
			Fast-mode Plus	0	-	µs
$t_{SU;DAT}$	data set-up time	[8][9]	Standard-mode	250	-	ns
			Fast-mode	100	-	ns
			Fast-mode Plus	50	-	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] tHD;DAT is the data hold time that is measured from the falling edge of SCL; applies to data in transmission and the acknowledge.

[3] A device must internally provide a hold time of at least 300 ns for the SDA signal (with respect to the V_{IH}(min) of the SCL signal) to bridge the undefined region of the falling edge of SCL.

[4] C_b = total capacitance of one bus line in pF. If mixed with Hs-mode devices, faster fall times are allowed.

[5] The maximum t_f for the SDA and SCL bus lines is specified at 300 ns. The maximum fall time for the SDA output stage t_f is specified at 250 ns. This allows series protection resistors to be connected in between the SDA and the SCL pins and the SDA/SCL bus lines without exceeding the maximum specified t_f.

[6] In Fast-mode Plus, fall time is specified the same for both output stage and bus timing. If series resistors are used, designers should allow for this when considering bus timing.

[7] The maximum $t_{HD;DAT}$ could be 3.45 µs and 0.9 µs for Standard-mode and Fast-mode but must be less than the maximum of $t_{VD;DAT}$ or $t_{VD;ACK}$ by a transition time. This maximum must only be met if the device does not stretch the LOW period (t_{LOW}) of the SCL signal. If the clock stretches the SCL, the data must be valid by the set-up time before it releases the clock.

[8] tSU;DAT is the data set-up time that is measured with respect to the rising edge of SCL; applies to data in transmission and the acknowledge.

[9] A Fast-mode I²C-bus device can be used in a Standard-mode I²C-bus system but the requirement $t_{SU;DAT}$ = 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line $t_{r(max)} + t_{SU;DAT}$ = 1000 + 250 = 1250 ns (according to the Standard-mode I²C-bus specification) before the SCL line is released. Also the acknowledge timing must meet this set-up time.

12. Application information

12.1 XTAL input

The input voltage to the on-chip oscillators is limited to 1.8 V. If the oscillator is driven by a clock in slave mode, it is recommended that the input be coupled through a capacitor with C_i = 100 pF. To limit the input voltage to the specified range, choose an additional capacitor to ground C_g which attenuates the input voltage by a factor $C_i/(C_i + C_g)$. In slave mode, a minimum of 200 mV(RMS) is needed.

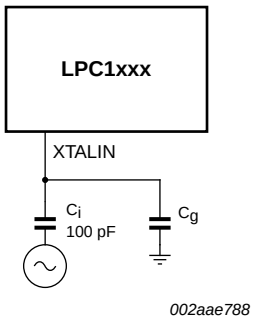


Fig 24. Slave mode operation of the on-chip oscillator

12.2 XTAL Printed Circuit Board (PCB) layout guidelines

The crystal should be connected on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors C_{x1},C_{x2}, and C_{x3} in case of third overtone crystal usage have a common ground plane. The external components must also be connected to the ground plain. Loops must be made as small as possible in order to keep the noise coupled in via the PCB as small as possible. Also parasitics should stay as small as possible. Values of C_{x1} and C_{x2} should be chosen smaller accordingly to the increase in parasitics of the PCB layout.